

1.5V Drive Pch MOSFET

RT1A050ZP

●Structure

Silicon P-channel MOSFET

●Features

- 1) Low on-resistance.
- 2) High power package.
- 3) Low voltage drive. (1.5V)

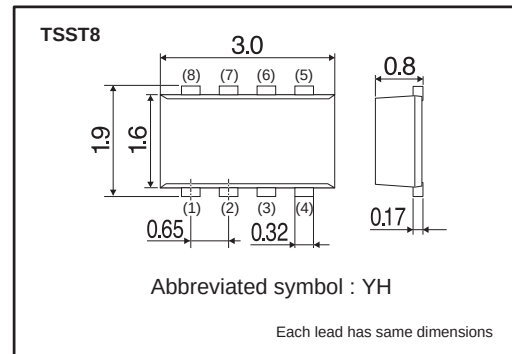
●Applications

Switching

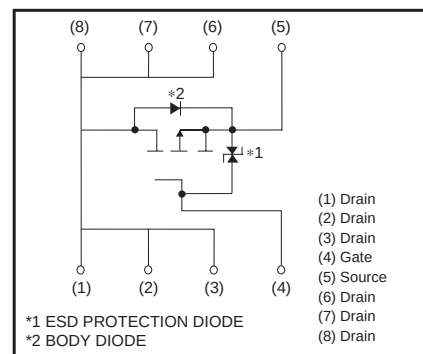
●Packaging specifications

Type	Package	Taping
	Code	TR
	Basic ordering unit(pieces)	3000
RT1A050ZP		○

●Dimensions (Unit : mm)



●Equivalent circuit



●Absolute maximum ratings (Ta=25°C)

Parameter		Symbol	Limits	Unit
Drain-source voltage		V_{DS}	-12	V
Gate-source voltage		V_{GS}	±10	V
Drain current	Continuous	I_D	±5	A
	Pulsed	I_{DP} *1	±20	A
Source current (Body diode)	Continuous	I_S	-1	A
	Pulsed	I_{SP} *1	-20	A
Total power dissipation		P_D	1.25	W *2
Channel temperature		T_{ch}	150	°C
Range of Storage temperature		T_{stg}	-55 to +150	°C

*1 $P_w \leq 10\mu s$, Duty cycle $\leq 1\%$

*2 When mounted on a ceramic board

●Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to ambient	$R_{th(ch-a)}$ *	100	°C / W

* When mounted on a ceramic board

●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I_{GSS}	—	—	±10	μA	$V_{GS}=±10V$, $V_{DS}=0V$
Drain-source breakdown voltage	$V_{(BR)DSS}$	−12	—	—	V	$I_D = -1mA$, $V_{GS}=0V$
Zero gate voltage drain current	I_{DSS}	—	—	−1	μA	$V_{DS} = -12V$, $V_{GS}=0V$
Gate threshold voltage	$V_{GS(th)}$	−0.3	—	−1.0	V	$V_{DS} = -6V$, $I_D = -1mA$
Static drain-source on-state resistance	$R_{DS(on)}^*$	—	19	26	mΩ	$I_D = -5A$, $V_{GS} = -4.5V$
		—	26	36	mΩ	$I_D = -2.5A$, $V_{GS} = -2.5V$
		—	34	50	mΩ	$I_D = -2.5A$, $V_{GS} = -1.8V$
		—	48	96	mΩ	$I_D = -1A$, $V_{GS} = -1.5V$
Forward transfer admittance	$ Y_{fs} ^*$	7	—	—	S	$V_{DS} = -6V$, $I_D = -5A$
Input capacitance	C_{iss}	—	2800	—	pF	$V_{DS} = -6V$
Output capacitance	C_{oss}	—	340	—	pF	$V_{GS}=0V$
Reverse transfer capacitance	C_{rss}	—	310	—	pF	$f=1MHz$
Turn-on delay time	$t_{d(on)}^*$	—	12	—	ns	$V_{DD} \doteq -6V$ $I_D = -2.5A$
Rise time	t_r^*	—	95	—	ns	$V_{GS} = -4.5V$
Turn-off delay time	$t_{d(off)}^*$	—	410	—	ns	$R_L \doteq 2.4\Omega$
Fall time	t_f^*	—	220	—	ns	$R_G=10\Omega$
Total gate charge	Q_g^*	—	34	—	nC	$V_{DD} \doteq -6V$ $R_L \doteq 1.2\Omega$
Gate-source charge	Q_{gs}^*	—	6.0	—	nC	$I_D = -5A$ $R_G=10\Omega$
Gate-drain charge	Q_{gd}^*	—	5.0	—	nC	$V_{GS} = -4.5V$

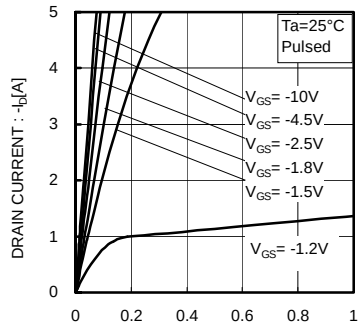
*Pulsed

●Body diode characteristics (Source -drain) (Ta=25°C)

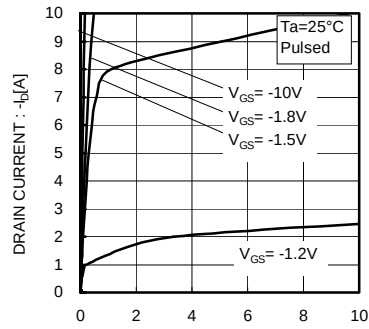
Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V_{SD}^*	—	—	−1.2	V	$I_S = -5A$, $V_{GS}=0V$

*Pulsed

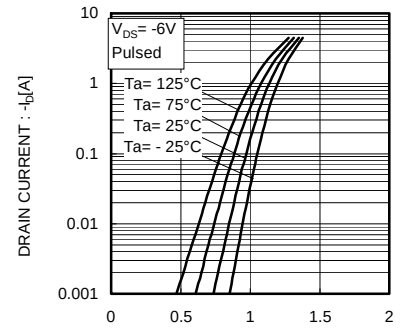
●Electrical characteristic curves



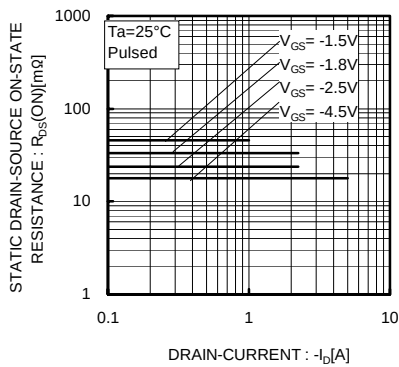
DRAIN-SOURCE VOLTAGE : $-V_{DS}$ [V]
Fig.1 Typical Output Characteristics (I)



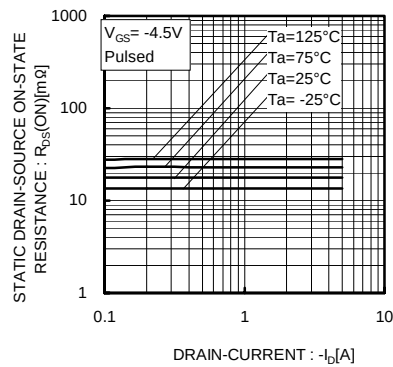
DRAIN-SOURCE VOLTAGE : $-V_{DS}$ [V]
Fig.2 Typical Output Characteristics(II)



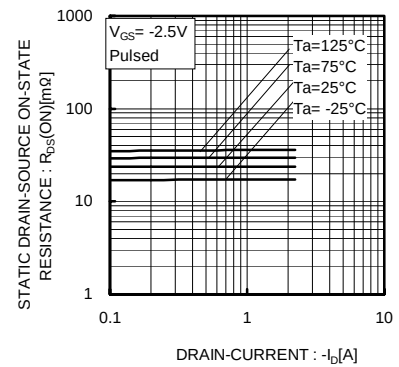
GATE-SOURCE VOLTAGE : $-V_{GS}$ [V]
Fig.3 Typical Transfer Characteristics



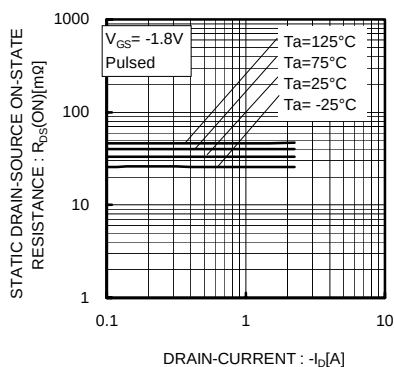
DRAIN-CURRENT : I_D [A]
Fig.4 Static Drain-Source On-State Resistance vs. Drain Current (I)



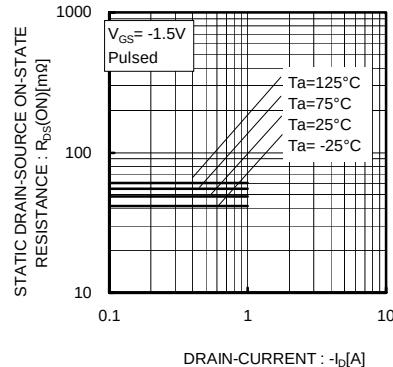
DRAIN-CURRENT : I_D [A]
Fig.5 Static Drain-Source On-State Resistance vs. Drain Current(II)



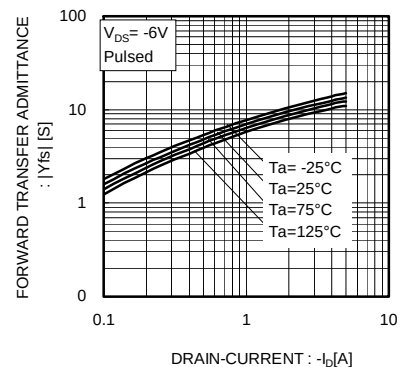
DRAIN-CURRENT : I_D [A]
Fig.6 Static Drain-Source On-State Resistance vs. Drain Current(III)



DRAIN-CURRENT : I_D [A]
Fig.7 Static Drain-Source On-State Resistance vs. Drain Current(IV)



DRAIN-CURRENT : I_D [A]
Fig.8 Static Drain-Source On-State Resistance vs. Drain Current(IV)



DRAIN-CURRENT : I_D [A]
Fig.9 Forward Transfer Admittance vs. Drain Current

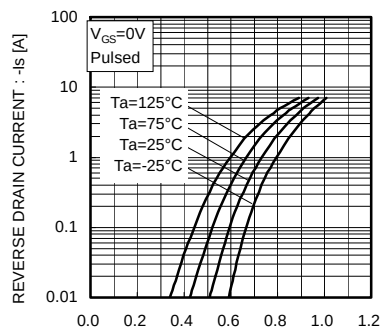


Fig.10 Reverse Drain Current vs. Source-Drain Voltage

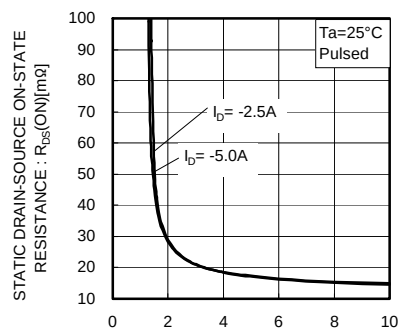


Fig.11 Static Drain-Source On-State Resistance vs. Gate Source Voltage

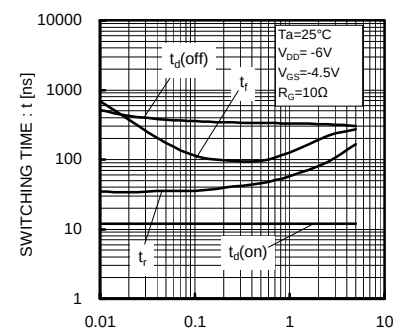


Fig.12 Switching Characteristics

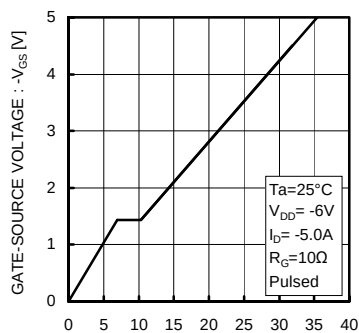


Fig.13 Dynamic Input Characteristics

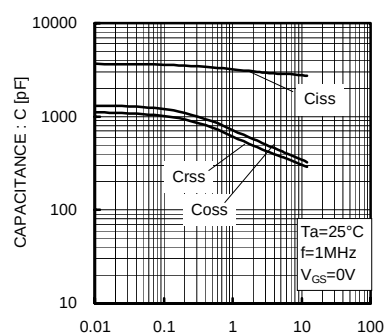


Fig.14 Typical Capacitance vs. Drain-Source Voltage

●Measurement circuits

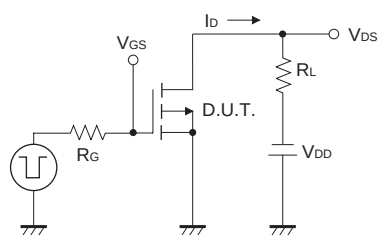


Fig.1-1 Switching Time Measurement Circuit

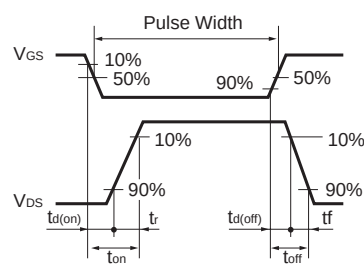


Fig.1-2 Switching Waveforms

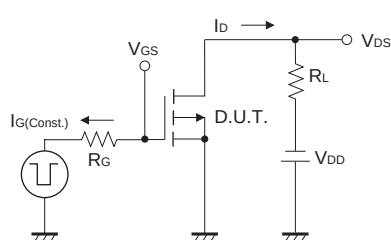


Fig.2-1 Gate Charge Measurement Circuit

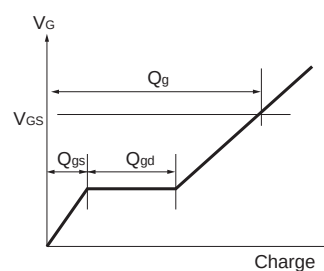


Fig.2-2 Gate Charge Waveform

●Notice

This product might cause chip aging and breakdown under the large electrified environment.
Please consider to design ESD protection circuit.

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